

WIRING SUBSTRATE, METHOD OF MANUFACTURING THE SAME  
AND SEMICONDUCTOR DEVICE

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ABSTRACT OF THE DISCLOSURE

10 A wiring substrate equipped with a rerouted wiring  
having one end connected to an electronic-part mounting  
pad for electrically connecting an electronic part and  
another end connected to an external-connection terminal.  
In the wiring substrate, a low-elasticity underlayer made  
of a material having a lower modulus of elasticity than  
15 that of a base material of the wiring substrate is  
disposed between the base material of the wiring  
substrate and each of the electronic-part mounting pad  
and the rerouted wiring. A method of manufacturing the  
wiring substrate and a semiconductor device using the  
20 wiring substrate are also disclosed.